

# Alternative Setup for Long-Duration Low- Duty-Cycle 600 °C Ambient Testing of SiC Integrated Circuits

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# Agenda



- Introduction
- Solution - Setup Overview
  - Compact Oven Overview
  - Testing Setup Overview
- Oven Enclosure Design and Testing
  - Mechanical Construction
  - Thermal Characterization
  - Oven Controller
- Measuring ICs in the Oven
- Conclusion

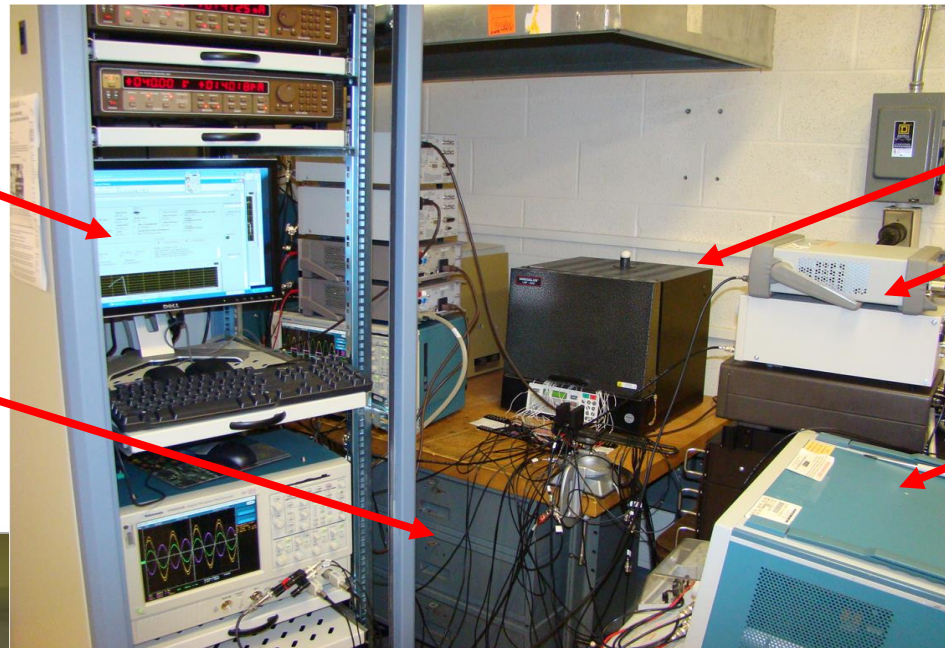
# Introduction – The Problem



- On the surface of Venus, the average temperature is  $460^{\circ}\text{C}$ 
  - Requires specialized high temperature electronics (SiC)
  - Commercial off the shelf (COTS) ovens are physically large
  - Each SiC IC testing requires unique wiring and measuring

Data Acquisition  
and Recording

Cabling mess



Large COTS Oven

Sourcing Devices

Power Supply



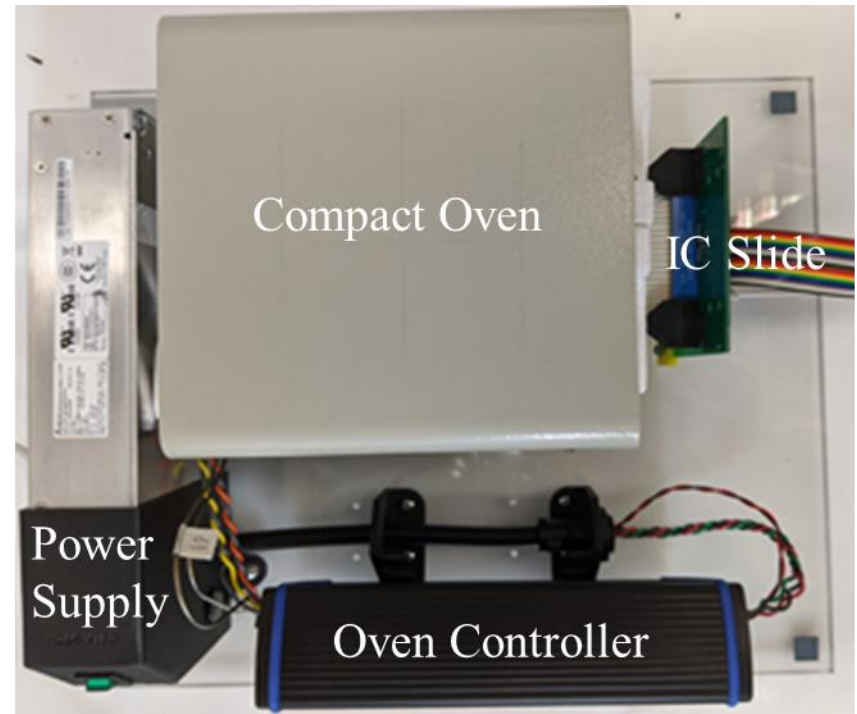
# Solution – Compact Oven Overview



- Team designed and created a smaller oven that can be connected nicely with a NI PXI system



Old COTS Oven vs New Compact Oven

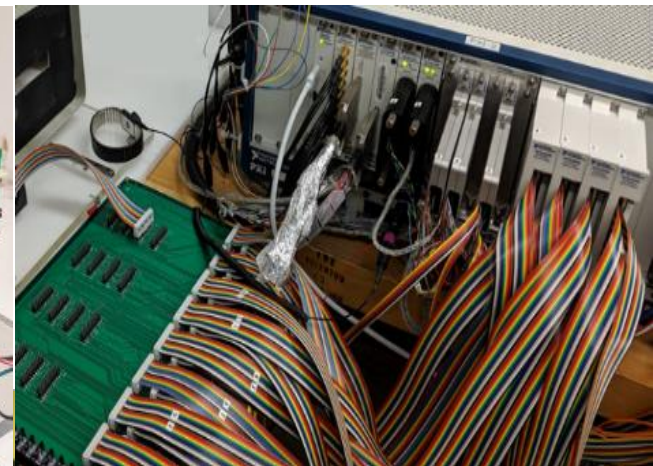
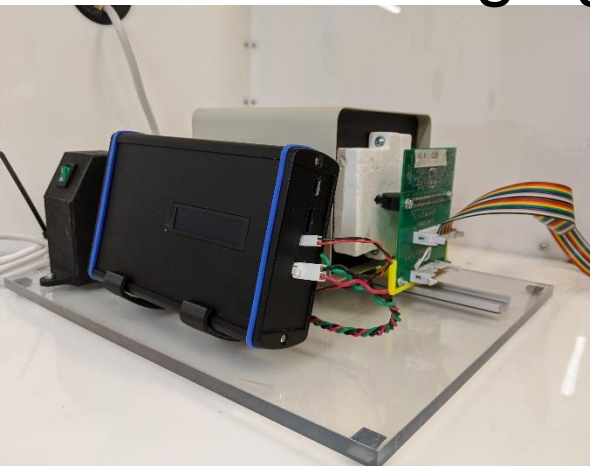


New Compact Oven Footprint

# Solution – Testing Setup Overview



- Oven substrate board: houses the DUT, mounts to the fixture board, and slides into the oven
- Fixture board: reroutes the DUT connections to signals and power pins for the NI PXI system
- Breakout board: provides a way to test 32 ovens without changing any wiring



New Compact Oven

Oven substrate board

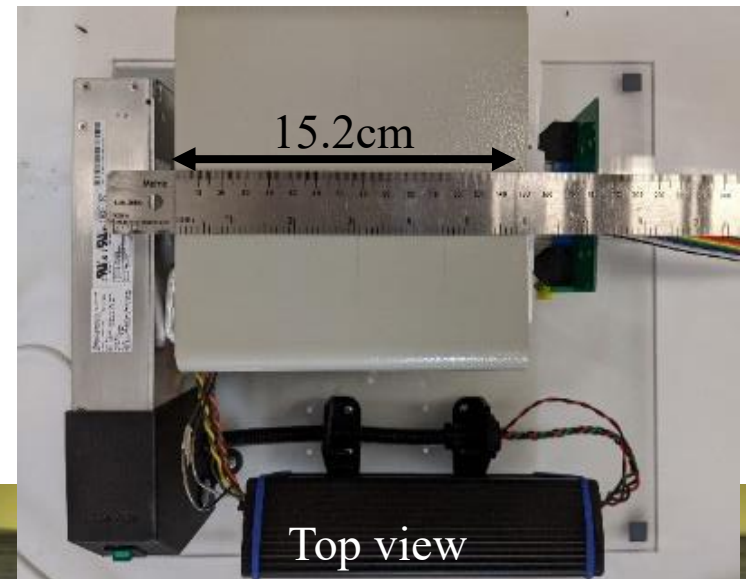
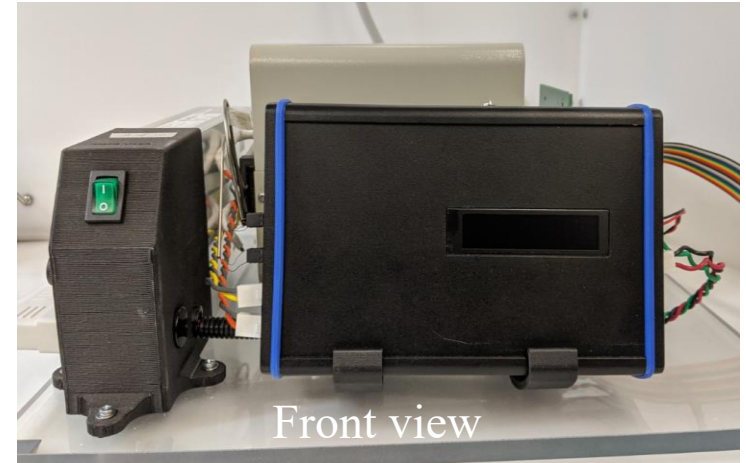
Fixture board

Breakout board to ovens and PXI matrix measurement unit

# Oven – Mechanical Construction



- Compact COTS empty metal box
  - 15.2 x 15.2 x 12.7 cm
- Oven electronics are physically separated
- Within frame
  - Custom ceramic heater cavity assembly
  - 2 types of high temperature insulation
    - Hard 1 ½ inch thick
    - Soft ½ inch thick





# Oven – Mechanical Construction Cont.

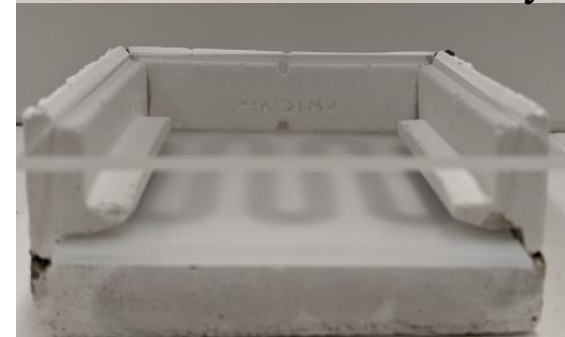


- Custom ceramic heater cavity is Silicon Oxide based
- The Custom ceramic heater cavity assembly contains:
  - Custom ceramic heater cavity
  - 2 COTS quartz plates
    - Either polished or unpolished
  - 2 COTS high temperature heating coils

## Custom ceramic heater construction process:



Front view - full assembly

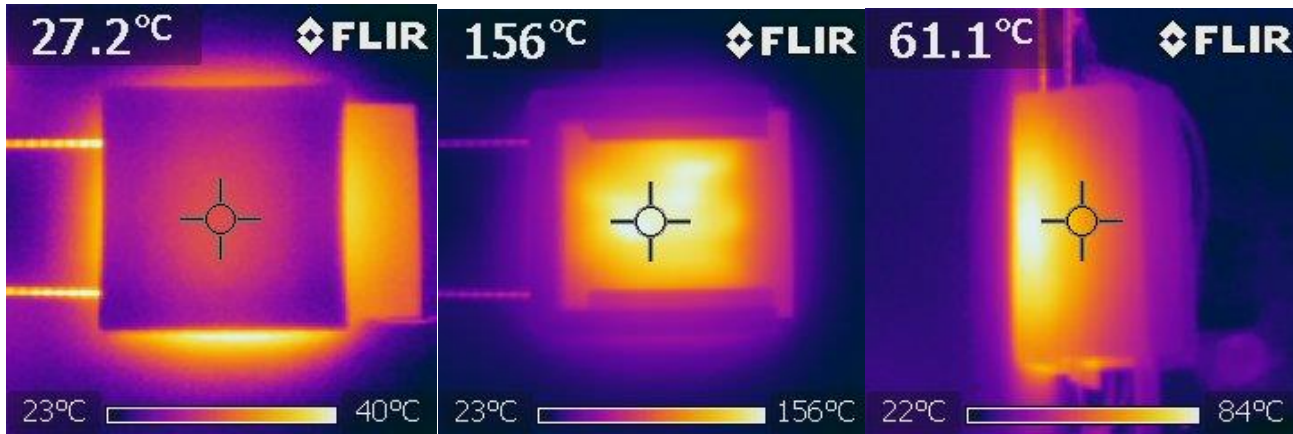


Front view - top heater off



Top view - top heater off

# Oven – Thermal Characterization



At 150°C: Top Ceramic on

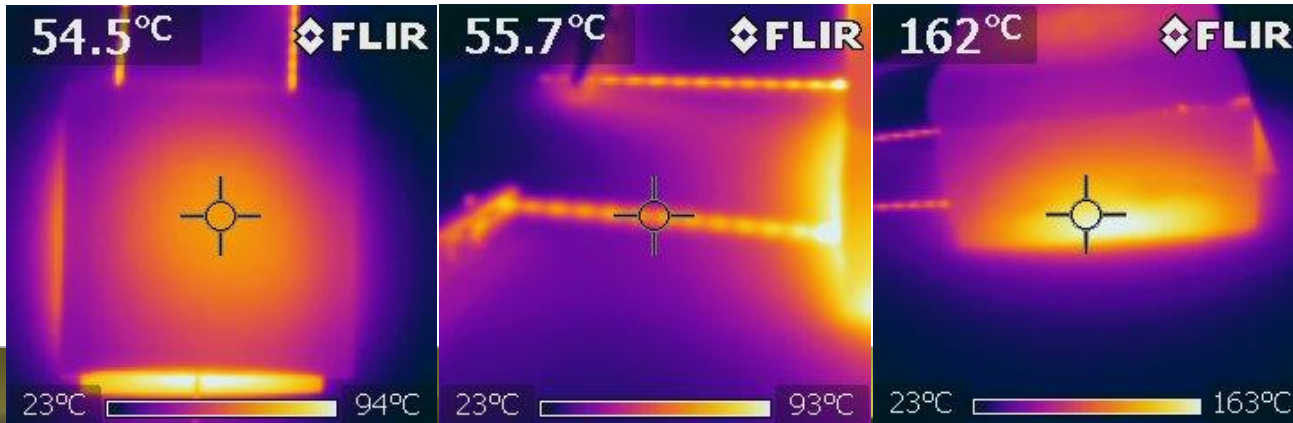
Bottom Quartz

Side with Top On

At 500°C: Top Ceramic on

Coil Leads

Side with Top On

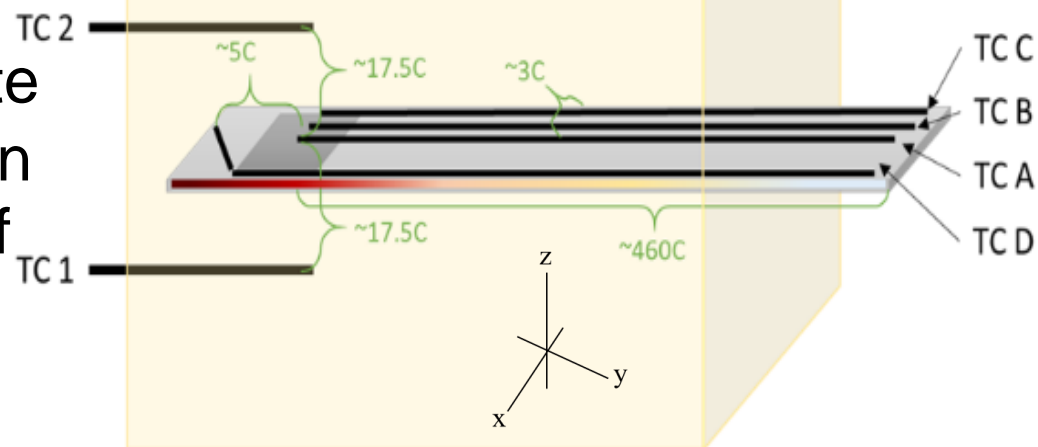
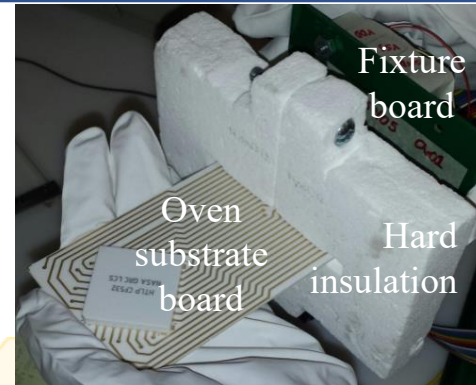




# Oven – Thermal Characterization Cont.



- Oven tested up to 600°C
- Few findings for low error:
  - Oven substrate board needs to be pushed all the way in
  - Use the hard high temperature insulation to close off the front of the oven
  - Be mindful of the ramp rate
  - Oven heating configuration provides different levels of power.

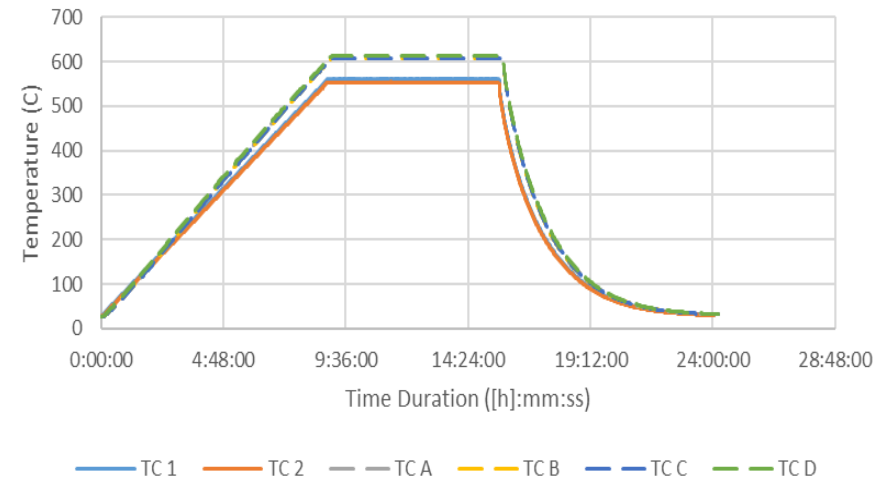


# Oven – Thermal Characterization Cont.

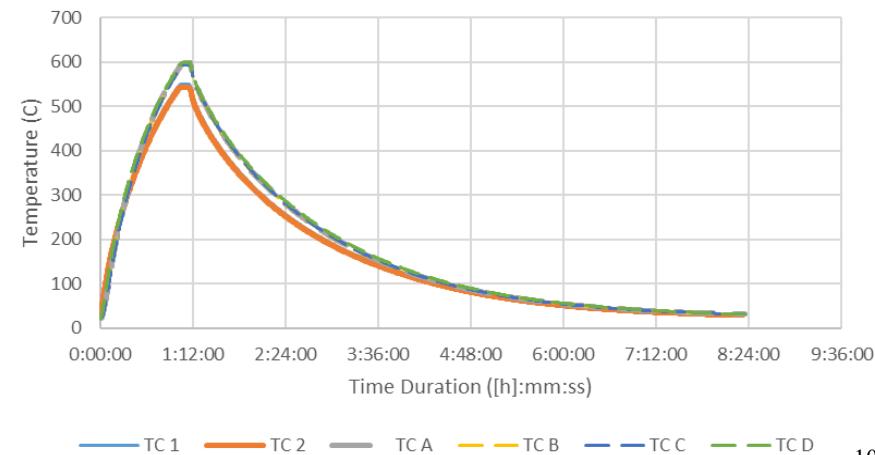


- $<5$  °C variance with oven substrate board pushed fully in
  - isolating both top and bottom heater
- TC1 and TC2 see less heat than the substrate
- Oven heat was unable to keep up with the ramp rate for the fast ramp up

Slow Ramp Up, Fast Ramp Down Board 8



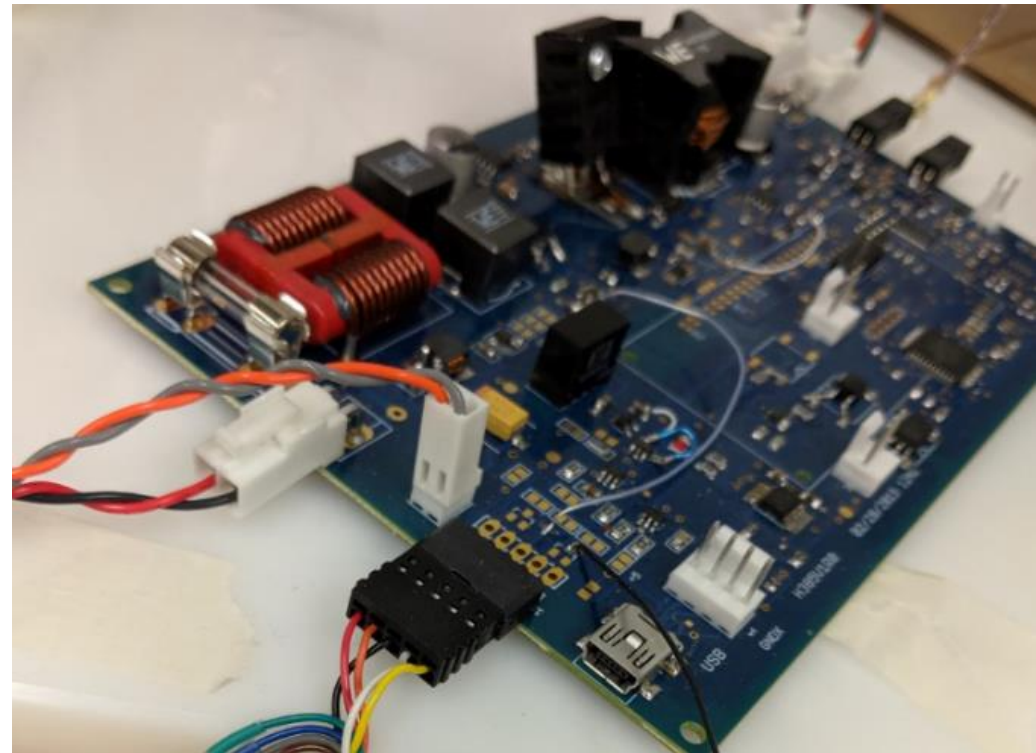
Fast Ramp Up and Down Board 8



# Oven – Controller



- Basic characteristics:
  - DC powered
  - Programmable
  - Separates the power between:
    - Control
    - Oven heating
  - Able to network ovens together



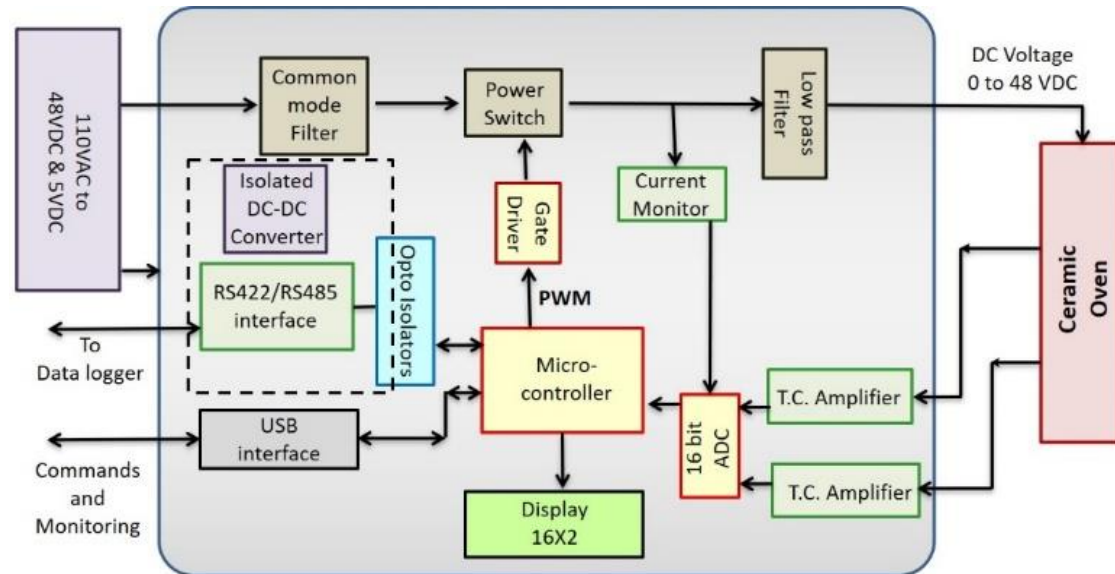


# Oven – Controller Cont.



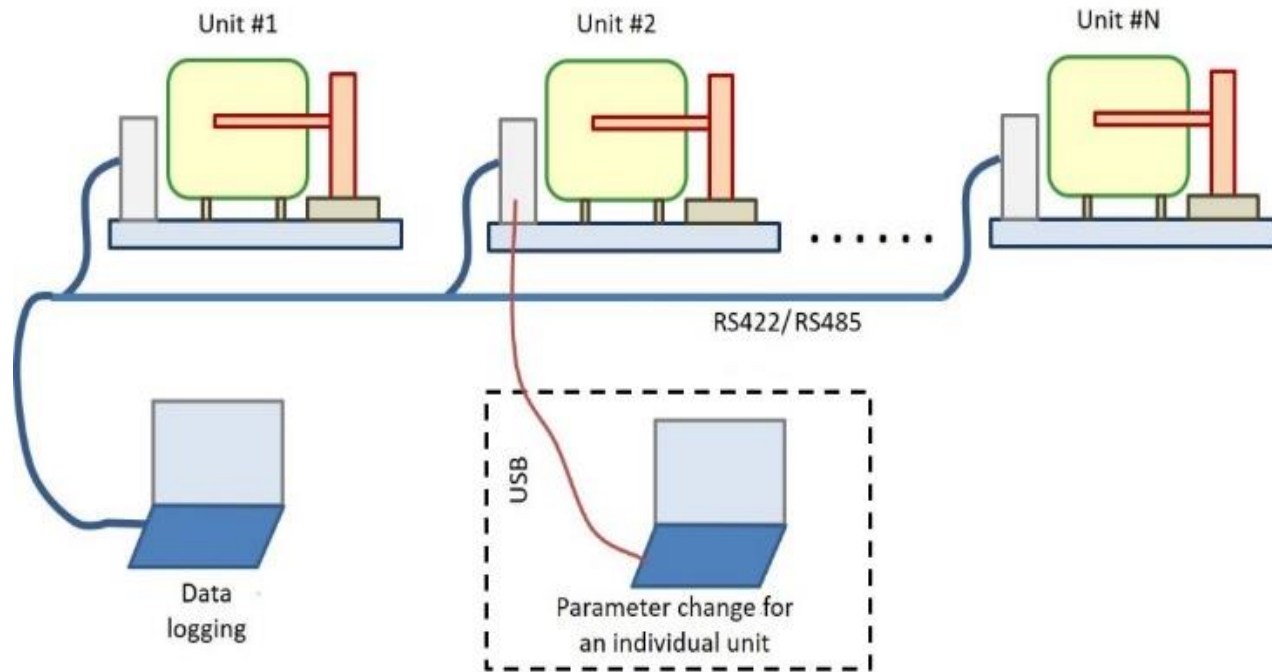
- Details of the controller:

- Controls oven target temperature and oven ramp rate independently
- Supplies up to 400 Watts
  - 120 Watts typical
- 48V line to heat ovens
- 5V line for control



Block diagram of oven controller

# Oven – Controller Cont.

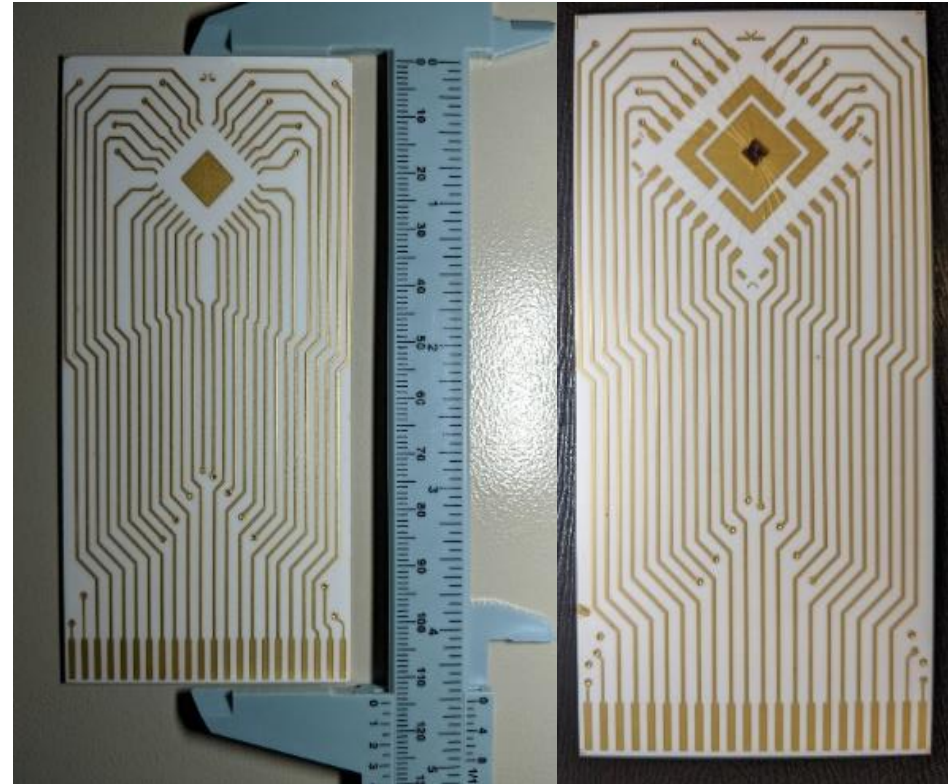


Using a second communication port, the ovens can be networked together and controlled by typing in the oven's specific identification number.

# Measuring ICs in the Ovens



- Ceramic package resides on a movable 11.43 cm long  $\text{Al}_2\text{O}_3$  substrate.
- Able to connect package via wire bonding
- Substrate dissipates the heat enough to connect to a room temperature connector
- This board connects to a NI PXI system for unique IC testing



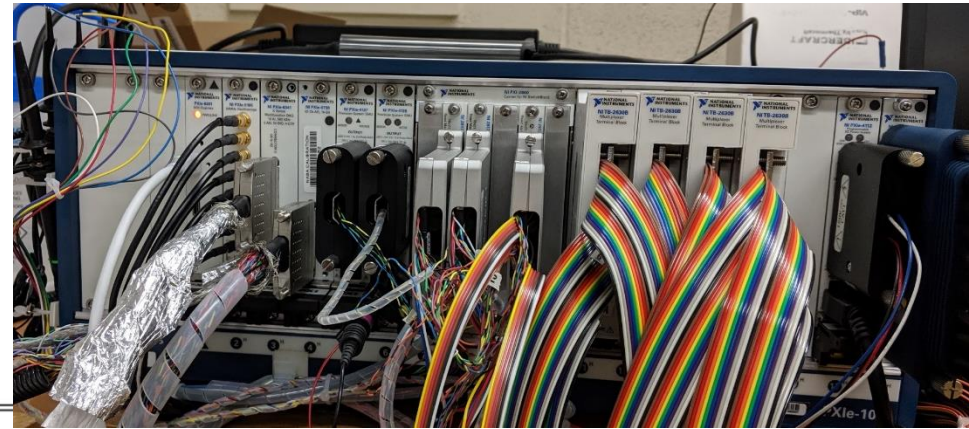


# Measuring ICs in the Ovens Cont.



## PXI system details

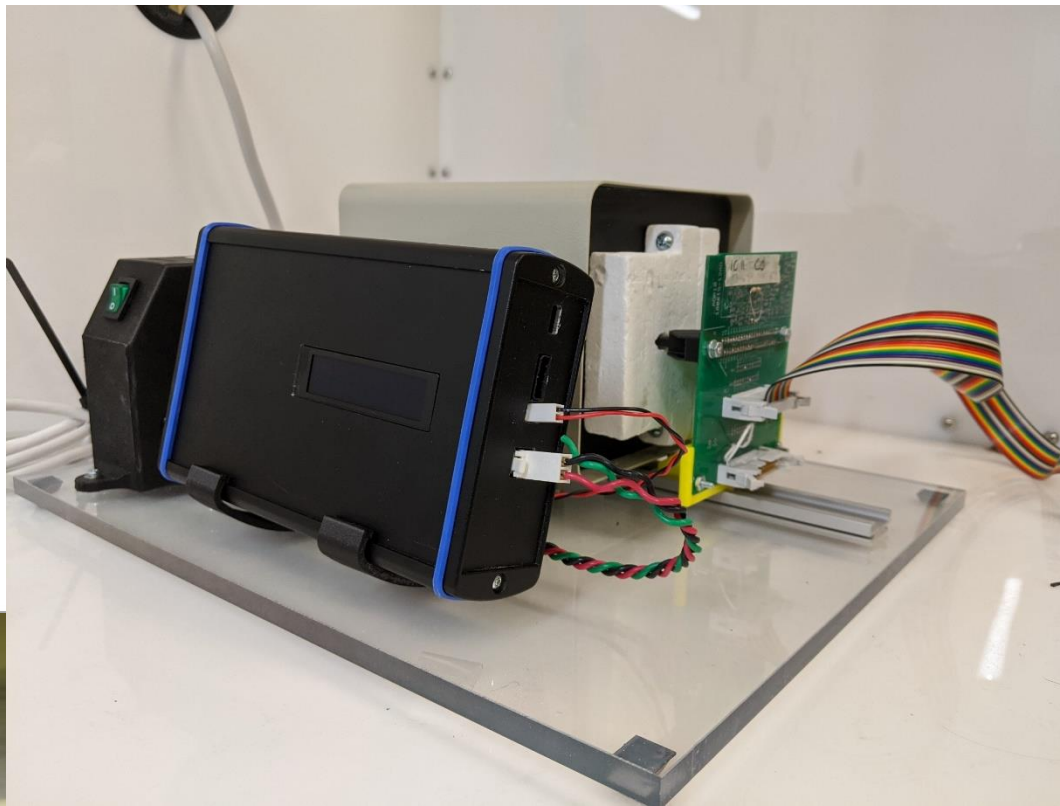
- Switching
  - Reed Relays
  - NI SwitchBlock
- Measuring
  - Oscilloscopes
  - Analog Inputs
  - SMU
- Sourcing
  - SMU
  - DC Power
  - Analog Outputs



# Conclusion



- Achieved a smaller footprint of high temperature ovens
- Achieved a scalable testing rig
- Ceramic heating block can reach up to 600C



# Questions?

